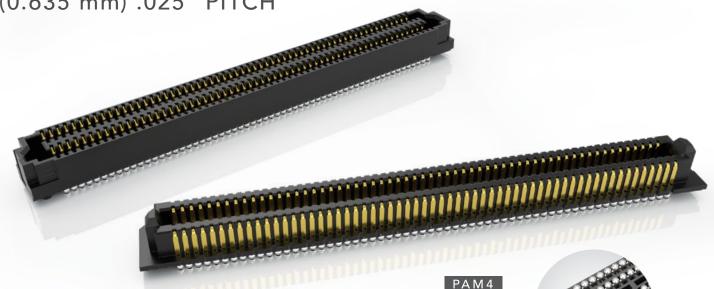
ACCELERATE HD

HIGH-DENSITY SLIM BODY ARRAYS

(0.635 mm) .025" PITCH



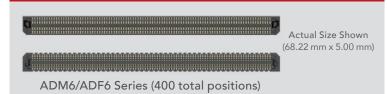
FEATURES & BENEFITS

- Up to 240 positions in 4-row design (400 positions in development)
- Low-profile 5 mm stack heights
- Slim 5 mm width body design
- Edge Rate® contact system optimized for signal integrity performance
- Open-pin-field for grounding and routing flexibility
- Right-angle (ADF6-RA) and other stack heights in development
- PCIe® 5.0 capable
- Compatible with mPower® (UMPT/UMPS) for a power signal solution



Solder ball technology for simplified processing

HIGHER DENSITY THAN PREVIOUS GENERATION STRIPS

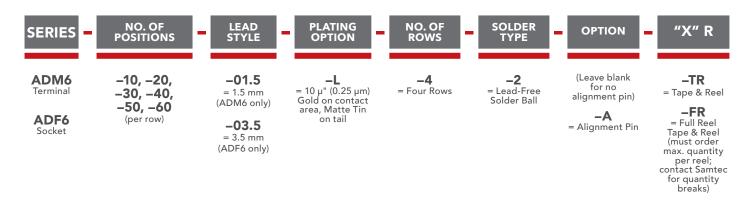


KEY SPECIFICATIONS

PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
(0.635 mm) .025"	40 - 240	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.34 A per pin (4 pins powered)	Testing now	Yes



(0.635 mm) .025" PITCH • SLIM BODY OPEN-PIN-FIELD ARRAYS

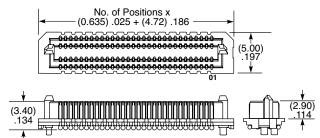


ADM6

Board Mates: ADF6

Standoffs:





MATED HEIGHTS *					
ADF6	ADM6 LEAD STYLE				
LEAD STYLE	-01.5				
-03.5	(5 mm) .197"				
* Processing conditions will affect mated height					

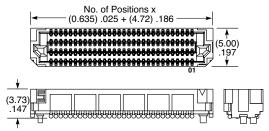
Frocessing conditions will affect mated neight

ADF6

Board Mates: ADM6

Standoffs: JSO





Notes:

Some sizes, styles and options are non-standard, non-returnable